INTEGRATED CIRCUITS

DATA SHEET

TDA8510J 26 W BTL and 2×13 W SE power amplifiers

Preliminary specification
File under Integrated Circuits, IC01

1998 May 18





TDA8510J

FEATURES

- Requires very few external components
- · High output power
- Low output offset voltage (BTL channel)
- · Fixed gain
- Diagnostic facility (distortion, short-circuit and temperature detection)
- · Good ripple rejection
- Mode select switch (operating, mute and standby)
- $\bullet\,$ AC and DC short-circuit safe to ground and to V_P
- · Low power dissipation in any short-circuit condition
- · Thermally protected
- · Reverse polarity safe

- Electrostatic discharge protection
- No switch-on/switch-off plop
- Flexible leads
- · Low thermal resistance
- · Identical inputs (inverting and non-inverting).

GENERAL DESCRIPTION

The TDA8510J is an integrated class-B output amplifier in a 17-lead single-in-line (SIL) power package. It contains a 26 W Bridge-Tied Load (BTL) amplifier and 2×13 W Single-Ended (SE) amplifiers.

The device is primarily developed for multi-media applications and active speaker systems (stereo with subwoofer).

QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
General		•	•			
V _P	supply voltage		6	15	18	V
I _{ORM}	repetitive peak output current		_	_	4	Α
I _{q(tot)}	total quiescent current		_	80	_	mA
I _{stb}	standby current		_	0.1	100	μΑ
BTL channel		•			•	
Po	output power	$R_L = 4 \Omega$; THD = 10%	_	26	_	W
SVRR	supply voltage ripple rejection		48	_	_	dB
V _{n(o)}	noise output voltage	$R_s = 0 \Omega$	_	70	_	μV
Z _i	input impedance		25	_	_	kΩ
$ \Delta V_{OO} $	DC output offset voltage		_	_	150	mV
Single-ended	l channels	•	•			
Po	output power	THD = 10%				
		$R_L = 4 \Omega$	_	7	_	W
		$R_L = 2 \Omega$	_	13	_	W
SVRR	supply voltage ripple rejection		48	_	-	dB
V _{n(o)}	noise output voltage	$R_s = 0 \Omega$	_	50	_	μV
Z _i	input impedance		50	_	_	kΩ

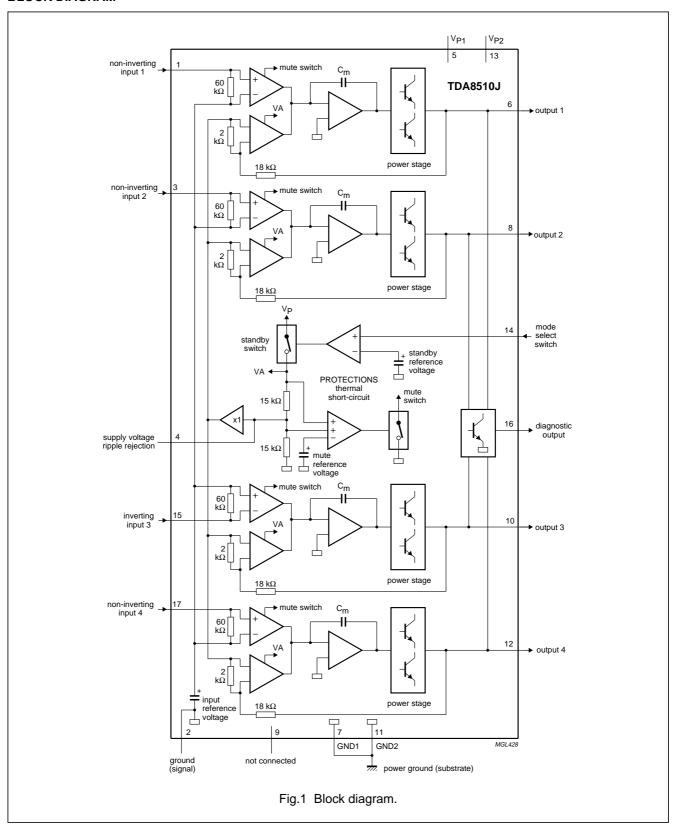
ORDERING INFORMATION

TYPE		PACKAGE	
NUMBER	NAME	DESCRIPTION	VERSION
TDA8510J	DBS17P	plastic DIL-bent-SIL power package; 17 leads (lead length 12 mm)	SOT243-1

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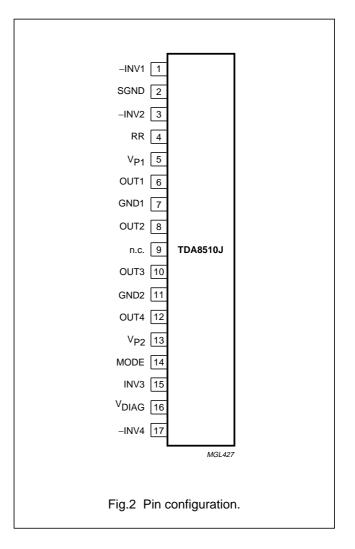
BLOCK DIAGRAM



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PINNING

SYMBOL	PIN	DESCRIPTION
-INV1	1	non-inverting input 1
SGND	2	signal ground
-INV2	3	non-inverting input 2
RR	4	supply voltage ripple rejection
V _{P1}	5	supply voltage 1
OUT1	6	output 1
GND1	7	power ground 1
OUT2	8	output 2
n.c.	9	not connected
OUT3	10	output 3
GND2	11	power ground 2
OUT4	12	output 4
V _{P2}	13	supply voltage 2
MODE	14	mode select switch input
INV3	15	inverting input 3
V _{DIAG}	16	diagnostic output
-INV4	17	non-inverting input 4



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FUNCTIONAL DESCRIPTION

The TDA8510J contains four identical amplifiers and can be used for two Single-Ended (SE) channels (fixed gain 20 dB) and one Bridge-Tied Load (BTL) channel (fixed gain 26 dB). Special features of the device are:

Mode select switch (pin 14)

- Low standby current (<100 μA)
- · Low switching current (low cost supply switch)
- · Mute facility.

To avoid switch-on plops, it is advised to keep the amplifier in the mute mode during ≥100 ms (charging of the input capacitors at pins 1, 3, 15 and 17). This can be achieved by:

- Microcontroller control
- External timing circuit (see Fig.8).

Diagnostic output (pin 16)

DYNAMIC DISTORTION DETECTOR (DDD)

At the onset of clipping of one or more output stages, the dynamic distortion detector becomes active and pin 16 goes LOW. This information can be used to drive a sound processor or DC volume control to attenuate the input signal and thus limit the distortion. The output level of pin 16 is independent of the number of channels that are clipping (see Figs 3 and 4).

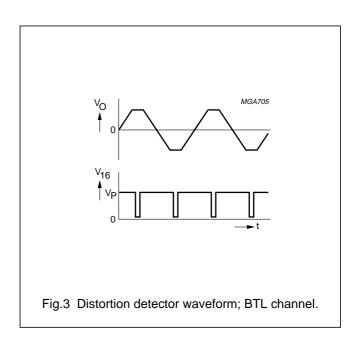
SHORT-CIRCUIT PROTECTION

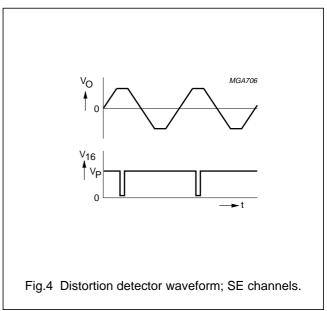
When a short-circuit occurs at one or more outputs to ground or to the supply voltage, the output stages are switched off until the short-circuit is removed and the device is switched on again, with a delay of approximately 20 ms, after removal of the short-circuit. During this short-circuit condition, pin 16 is continuously LOW.

When a short-circuit across the load of one or more channels occurs the output stages are switched off for approximately 20 ms. After that time it is checked during approximately 50 μs to see whether the short-circuit is still present. Due to this duty cycle of 50 $\mu s/20$ ms the average current consumption during this short-circuit condition is very low (approximately 40 mA).

During this short-circuit condition, pin 16 is LOW for 20 ms and HIGH for 50 μs (see Fig.5).

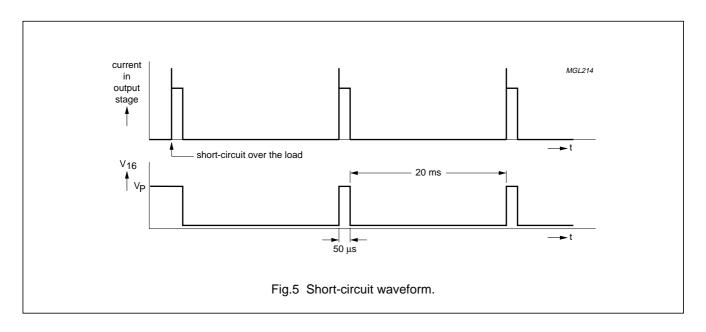
The power dissipation in any short-circuit condition is very low.





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TEMPERATURE DETECTION

When the virtual junction temperature $T_{\nu j}$ reaches 150 °C, pin 16 will be active LOW.

OPEN-COLLECTOR OUTPUT

Pin 16 is an open-collector output, which allows pin 16 of more devices being tied together.

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

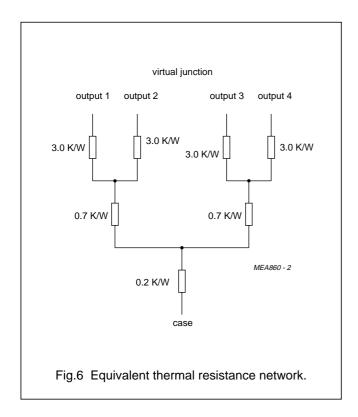
SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _P	supply voltage		_	18	V
I _{OSM}	non-repetitive peak output current		_	6	Α
I _{ORM}	repetitive peak output current		_	4	Α
V _{sc}	AC and DC short-circuit safe voltage		_	18	V
V _{rp}	reverse polarity voltage		_	6	V
P _{tot}	total power dissipation		_	60	W
T _{stg}	storage temperature		-55	+150	°C
T _{amb}	operating ambient temperature		-40	+85	°C
T _{vj}	virtual junction temperature		_	150	°C

THERMAL CHARACTERISTICS

In accordance with IEC 747-1.

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th(j-a)}	thermal resistance from junction to ambient	in free air	40	K/W
R _{th(j-c)}	thermal resistance from junction to case (see Fig.6)		1.3	K/W

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DC CHARACTERISTICS

 V_P = 15 V; T_{amb} = 25 °C; measured in Fig.7; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Supply				•	•		
V _P	supply voltage	note 1	6	15	18	V	
I _{q(tot)}	total quiescent current		_	80	160	mA	
Vo	DC output voltage		_	6.9	_	V	
$ \Delta V_{OO} $	DC output offset voltage	note 2	_	_	150	mV	
Mode select s	witch						
V _{SW(on)}	switch-on voltage level		8.5	_	_	V	
MUTE CONDITIO	N		,				
V _{mute}	mute voltage		3.3	_	6.4	V	
Vo	output voltage in mute position	$V_{I(max)} = 1 \text{ V; } f = 1 \text{ kHz}$	_	_	2	mV	
ΔV ₀₀	DC output offset voltage	note 2	_	_	150	mV	
STANDBY CONDI	TION						
V _{stb}	standby voltage		0	_	2	V	
I _{stb}	standby current		_	_	100	μΑ	
I _{sw(on)}	switch-on current		_	12	40	μΑ	
Diagnostic ou	Diagnostic output (pin 16)						
V_{DIAG}	diagnostic output voltage	any short-circuit or clipping	_	_	0.6	V	

Notes

- 1. The circuit is DC adjusted at V_P = 6 to 18 V and AC operating at V_P = 8.5 to 18 V.
- 2. Only for BTL channel (V_{12-10}).

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AC CHARACTERISTICS

 V_P = 15 V; f = 1 kHz; T_{amb} = 25 °C; measure in Fig.7; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
BTL channe	el		•			
Po	output power	note 1				
		THD = 0.5%	16	20	_	W
		THD = 10%	22	26	_	W
THD	total harmonic distortion	P _o = 1 W	_	0.1	_	%
В	power bandwidth	THD = 0.5%;	_	20 to	_	Hz
		$P_0 = -1$ dB; with respect to 16 W		15000		
f _{ro(I)}	low frequency roll-off	at -1 dB; note 2	_	25	_	Hz
f _{ro(h)}	high frequency roll-off	at -1 dB	20	_	_	kHz
G _v	closed loop voltage gain		25	26	27	dB
SVRR	supply voltage ripple rejection	note 3				
		on	48	_	_	dB
		mute	48	_	_	dB
		standby	80	_	_	dB
Z _i	input impedance		25	30	38	kΩ
V _{n(o)}	noise output voltage	on; $R_s = 0 \Omega$; note 4	_	70	_	μV
		on; $R_s = 10 \text{ k}\Omega$; note 4	_	100	200	μV
		mute; notes 4 and 5	_	60	_	μV
$\alpha_{ t cs}$	channel separation	$R_s = 10 \text{ k}\Omega$	40	_	_	dB
DYNAMIC DIS	TORTION DETECTOR					•
THD	total harmonic distortion	V ₁₆ ≤ 0.6 V; no short-circuit	_	10	_	%

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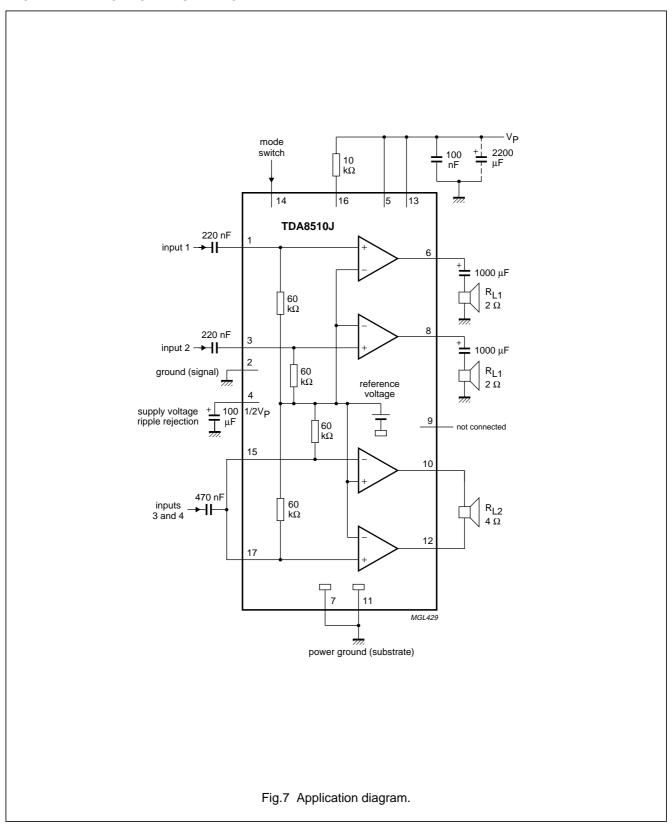
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Single-ende	ed channels			•	•	
Po	output power	note 1				
		THD = 0.5%	8	10	_	W
		THD = 10%	11	13	_	W
		$R_{L1} = 4 \Omega$; note 1				
		THD = 0.5%	_	5.5	_	W
		THD = 10%	_	7	_	W
THD	total harmonic distortion	P _o = 1 W	_	0.1	_	%
f _{ro(I)}	low frequency roll-off	at -1 dB; note 2	_	25	_	Hz
f _{ro(h)}	high frequency roll-off	at -1 dB	20	_	_	kHz
G _v	closed loop voltage gain		19	20	21	dB
SVRR	supply voltage ripple rejection	note 3				
		on	48	_	_	dB
		mute	48	_	_	dB
		standby	80	_	_	dB
$ Z_i $	input impedance		50	60	75	kΩ
V _{n(o)}	noise output voltage	on; $R_s = 0 \Omega$; note 4	_	50	_	μV
		on; $R_s = 10 \text{ k}\Omega$; note 4	_	70	100	μV
		mute; notes 4 and 5	_	50	_	μV
$\alpha_{ t CS}$	channel separation	$R_s = 10 \text{ k}\Omega$	40	_	_	dB
$ \Delta G_v $	channel unbalance		_	_	1	dB
DYNAMIC DIS	TORTION DETECTOR					
THD	total harmonic distortion	V ₁₆ ≤ 0.6 V; no short-circuit	_	10	_	%

Notes

- 1. Output power is measured directly at the output pins of the IC.
- 2. Frequency response externally fixed.
- 3. Ripple rejection measured at the output with a source impedance of 0 Ω , maximum ripple amplitude of 2 V (p-p) and at a frequency of between 100 Hz and 10 kHz.
- 4. Noise measured in a bandwidth of 20 Hz to 20 kHz.
- 5. Noise output voltage independent of R_s (V_i = 0 V).

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TEST AND APPLICATION INFORMATION



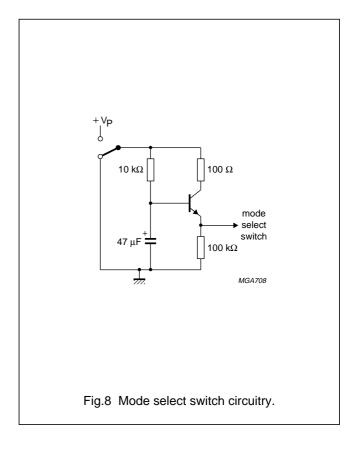
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Mode select switch

To avoid switch-on plops, it is advised to keep the amplifier in the mute mode during >100 ms (charging of the input capacitors at pins 1, 3, 15 and 17.

The circuit in Fig.8 slowly ramps up the voltage at the mode select switch pin when switching on and results in fast muting when switching off.



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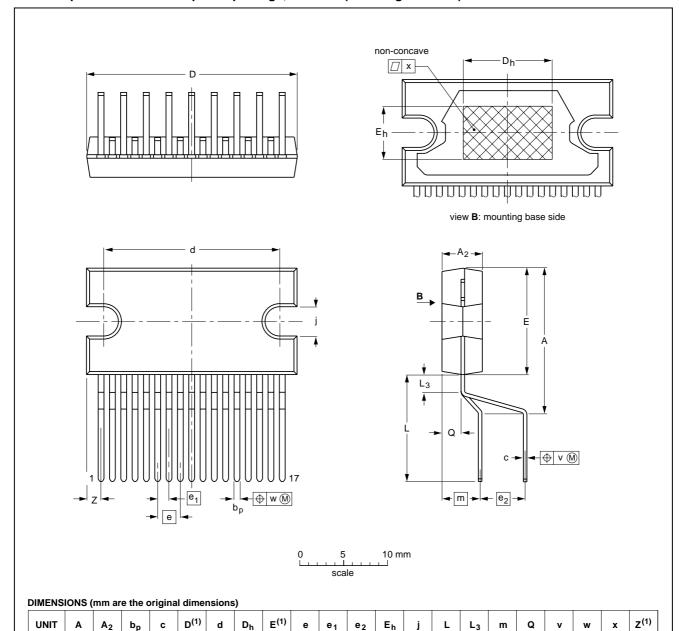
PACKAGE OUTLINE

DBS17P: plastic DIL-bent-SIL power package; 17 leads (lead length 12 mm)

SOT243-1

2.00 1.45

0.03



Note

17.0 15.5 4.6 4.2 0.75 0.60 0.48 0.38

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

24.0 23.6 20.0

19.6

10

12.2 11.8

2.54

1.27

5.08

OUTLINE		REFER	ENCES	EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE
SOT243-1					95-03-11 97-12-16

12.4 11.0

2.4

1.6

4.3

8.0

3.4

3.1

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SOLDERING

Introduction

There is no soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and surface mounted components are mixed on one printed-circuit board. However, wave soldering is not always suitable for surface mounted ICs, or for printed-circuits with high population densities. In these situations reflow soldering is often used.

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our "Data Handbook IC26; Integrated Circuit Packages" (order code 9398 652 90011).

Soldering by dipping or by wave

The maximum permissible temperature of the solder is 260 °C; solder at this temperature must not be in contact with the joint for more than 5 seconds. The total contact time of successive solder waves must not exceed 5 seconds.

The device may be mounted up to the seating plane, but the temperature of the plastic body must not exceed the specified maximum storage temperature ($T_{stg\ max}$). If the printed-circuit board has been pre-heated, forced cooling may be necessary immediately after soldering to keep the temperature within the permissible limit.

Repairing soldered joints

Apply a low voltage soldering iron (less than 24 V) to the lead(s) of the package, below the seating plane or not more than 2 mm above it. If the temperature of the soldering iron bit is less than 300 °C it may remain in contact for up to 10 seconds. If the bit temperature is between 300 and 400 °C, contact may be up to 5 seconds.

DEFINITIONS

Data sheet status	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.
Limiting values	

Limiting values

Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

Application information

Where application information is given, it is advisory and does not form part of the specification.

LIFE SUPPORT APPLICATIONS

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